

SKM 300GB126D



SEMITRANS® 3

Trench IGBT Module

SKM 300GB126D

Preliminary Data

Features

- Trench = Trenchgate technology
- V_{CEsat} with positive temperature coefficient
- High short circuit capability, self limiting to $6 \times I_C$

Typical Applications

- Electronic welders
- AC inverter drives
- UPS



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Absolute Maximum Ratings		$T_c = 25\text{ °C}$, unless otherwise specified		
Symbol	Conditions	Values		Units
IGBT				
V_{CES}	$T_j = 25\text{ °C}$	1200		V
I_C	$T_j = 150\text{ °C}$	$T_{case} = 25\text{ °C}$	310	A
		$T_{case} = 80\text{ °C}$	200	A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$	400		A
V_{GES}		± 20		V
t_{psc}	$V_{CC} = 600\text{ V}; V_{GE} \leq 20\text{ V}; T_j = 125\text{ °C}$ $V_{CES} < 1200\text{ V}$	10		µs
Inverse Diode				
I_F	$T_j = 150\text{ °C}$	$T_{case} = 25\text{ °C}$	250	A
		$T_{case} = 80\text{ °C}$	170	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$	400		A
Module				
$I_{t(RMS)}$		500		A
T_{vj}		- 40 ... + 150		°C
T_{stg}		-40...+125		°C
V_{isol}	AC, 1 min.	4000		V

Characteristics		$T_c = 25\text{ °C}$, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 8\text{ mA}$	5	5,8	6,5	V
I_{CES}	$V_{GE} = 0\text{ V}, V_{CE} = V_{CES}$		$T_j = 25\text{ °C}$ 0,1	0,3	mA
V_{CE0}			$T_j = 25\text{ °C}$ 1	1,2	V
			$T_j = 125\text{ °C}$ 0,9	1,1	V
r_{CE}	$V_{GE} = 15\text{ V}$		$T_j = 25\text{ °C}$ 3,5	4,7	mΩ
			$T_j = 125\text{ °C}$ 5,5	6,8	mΩ
$V_{CE(sat)}$	$I_{Cnom} = 200\text{ A}, V_{GE} = 15\text{ V}$		$T_j = 25\text{ °C}_{chiplev.}$ 1,7	2,15	V
			$T_j = 125\text{ °C}_{chiplev.}$ 2	2,45	V
C_{ies}	$V_{CE} = 25, V_{GE} = 0\text{ V}$		15		nF
C_{oes}			1,2		nF
C_{res}			1,1		nF
Q_G	$V_{GE} = -8\text{ V} - +20\text{ V}$		1800		nC
R_{Gint}	$T_j = 25\text{ °C}$		3,8		Ω
$t_{d(on)}$	$R_{Gon} = 1,5\text{ Ω}$	$V_{CC} = 600\text{ V}$ $I_{Cnom} = 200\text{ A}$		280	ns
t_r				37	ns
E_{on}	$R_{Goff} = 1,5\text{ Ω}$	$T_j = 125\text{ °C}$ $V_{GE} = \pm 15\text{ V}$		21	mJ
$t_{d(off)}$				560	ns
t_f				100	ns
E_{off}				33	mJ
$R_{th(j-c)}$	per IGBT			0,12	K/W



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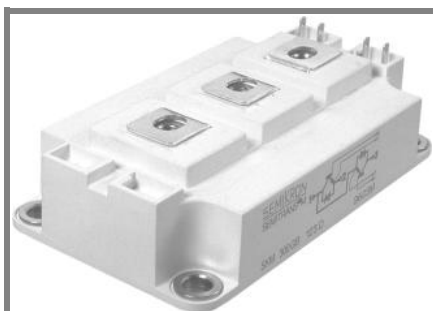
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Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
Inverse diode					
$V_F = V_{EC}$	$I_{Fnom} = 200 \text{ A}; V_{GE} = 0 \text{ V}$	$T_j = 25 \text{ }^\circ\text{C}_{chiplev.}$	1,6	1,8	V
		$T_j = 125 \text{ }^\circ\text{C}_{chiplev.}$	1,6	1,8	V
V_{F0}		$T_j = 25 \text{ }^\circ\text{C}$	1	1,1	V
		$T_j = 125 \text{ }^\circ\text{C}$	0,8	0,9	V
r_F		$T_j = 25 \text{ }^\circ\text{C}$	3	3,5	mΩ
		$T_j = 125 \text{ }^\circ\text{C}$	4	4,5	mΩ
I_{RRM}	$I_{Fnom} = 200 \text{ A}$	$T_j = 125 \text{ }^\circ\text{C}$	290		A
Q_{rr}	$di/dt = 6200 \text{ A}/\mu\text{s}$		44		μC
E_{rr}	$V_{GE} = -15 \text{ V}; V_{CC} = 600 \text{ V}$		18		mJ
$R_{th(j-c)D}$	per diode			0,25	K/W
Module					
L_{CE}			15	20	nH
$R_{CC'+EE'}$	res., terminal-chip	$T_{case} = 25 \text{ }^\circ\text{C}$	0,35		mΩ
		$T_{case} = 125 \text{ }^\circ\text{C}$	0,5		mΩ
$R_{th(c-s)}$	per module			0,038	K/W
M_s	to heat sink M6		3	5	Nm
M_t	to terminals M6		2,5	5	Nm
w				325	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.

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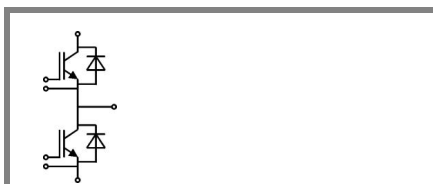
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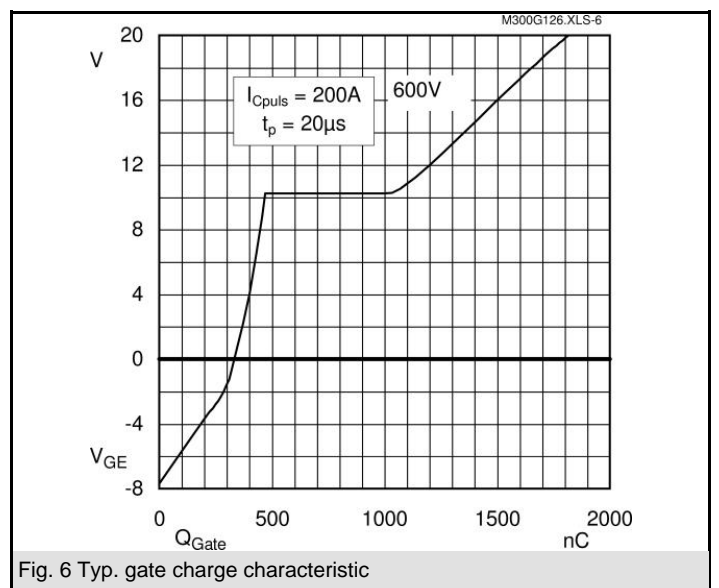
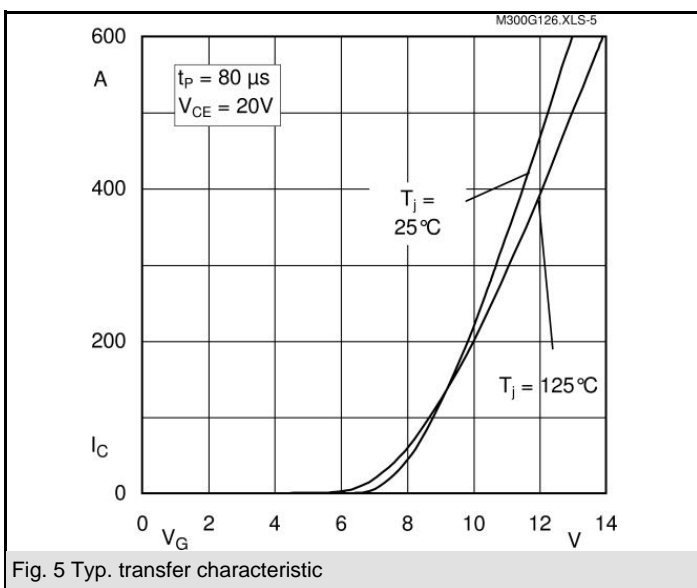
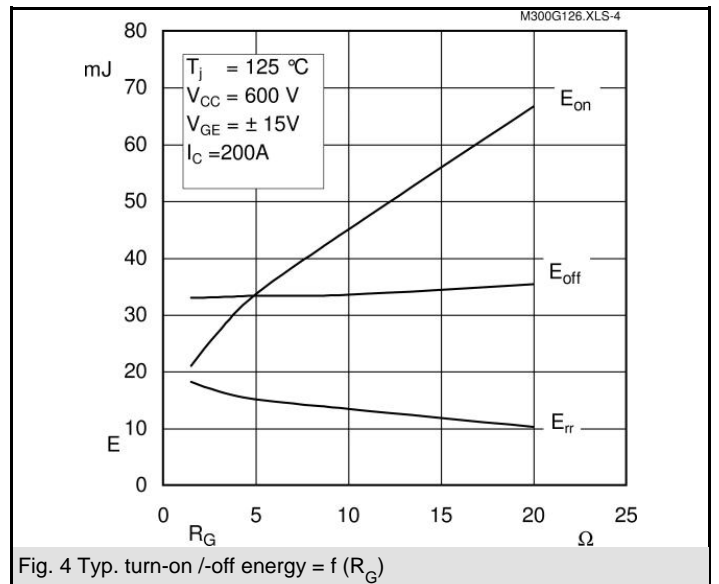
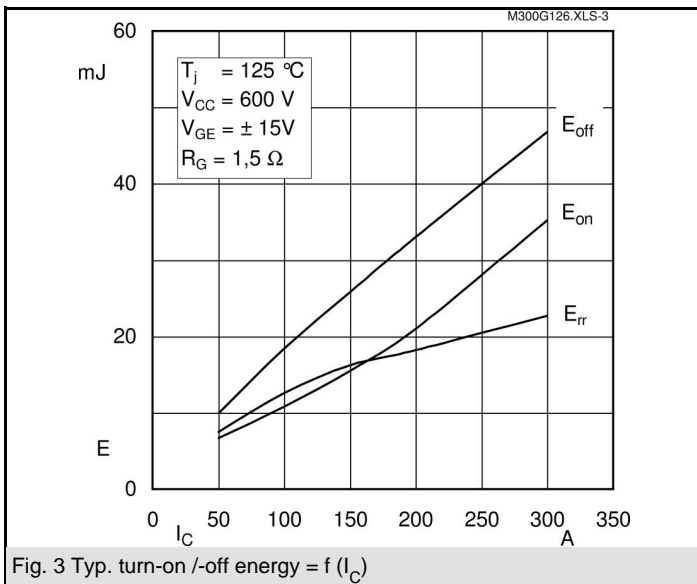
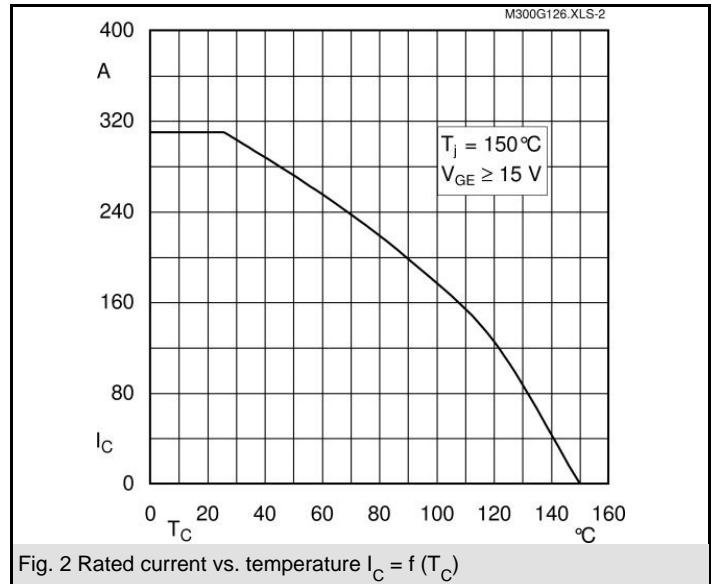
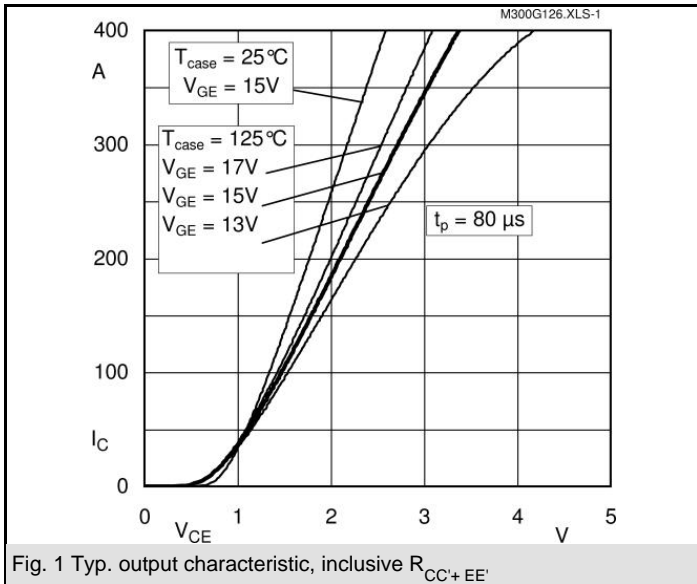
Typical Applications

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Z_{th}		Conditions	Values	Units
Symbol				
$Z_{th(j-c)I}$				
$R_{\theta j-c}$	$i = 1$		80	mk/W
$R_{\theta j-c}$	$i = 2$		30	mk/W
$R_{\theta j-c}$	$i = 3$		8,5	mk/W
$R_{\theta j-c}$	$i = 4$		1,5	mk/W
$\tau_{\theta j-c}$	$i = 1$		0,0576	s
$\tau_{\theta j-c}$	$i = 2$		0,01	s
$\tau_{\theta j-c}$	$i = 3$		0,002	s
$\tau_{\theta j-c}$	$i = 4$		0,0002	s
Symbol				
$Z_{th(j-c)D}$				
$R_{\theta j-c}$	$i = 1$		150	mk/W
$R_{\theta j-c}$	$i = 2$		75	mk/W
$R_{\theta j-c}$	$i = 3$		22	mk/W
$R_{\theta j-c}$	$i = 4$		3	mk/W
$\tau_{\theta j-c}$	$i = 1$		0,0331	s
$\tau_{\theta j-c}$	$i = 2$		0,0113	s
$\tau_{\theta j-c}$	$i = 3$		0,0012	s
$\tau_{\theta j-c}$	$i = 4$		0,001	s



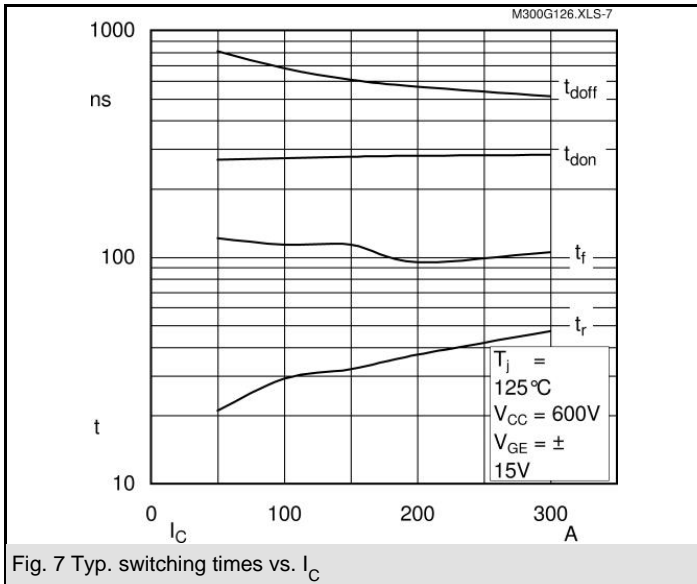


Fig. 7 Typ. switching times vs. I_C

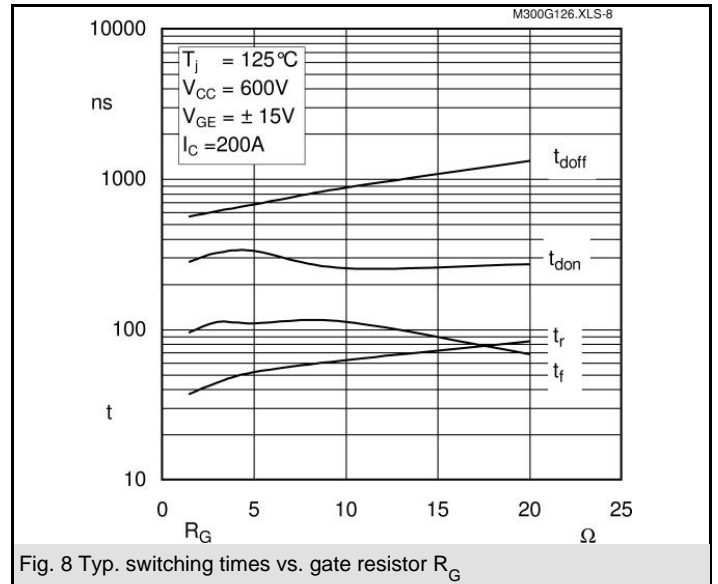


Fig. 8 Typ. switching times vs. gate resistor R_G

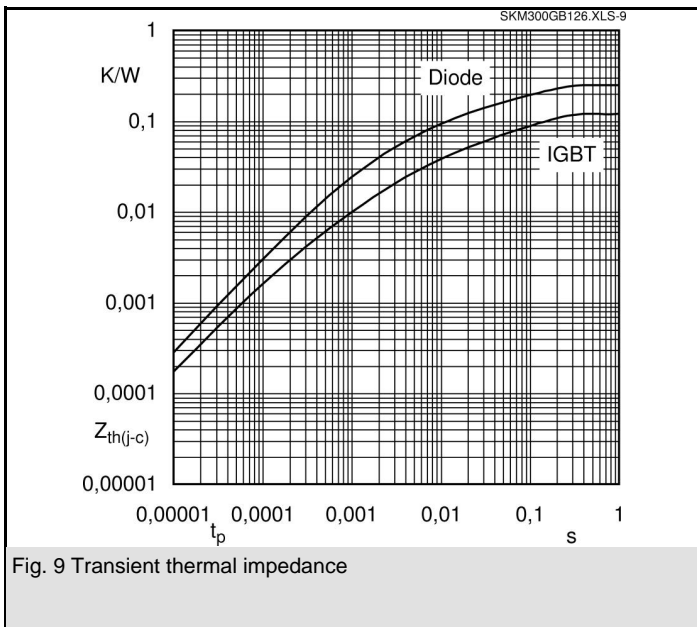


Fig. 9 Transient thermal impedance

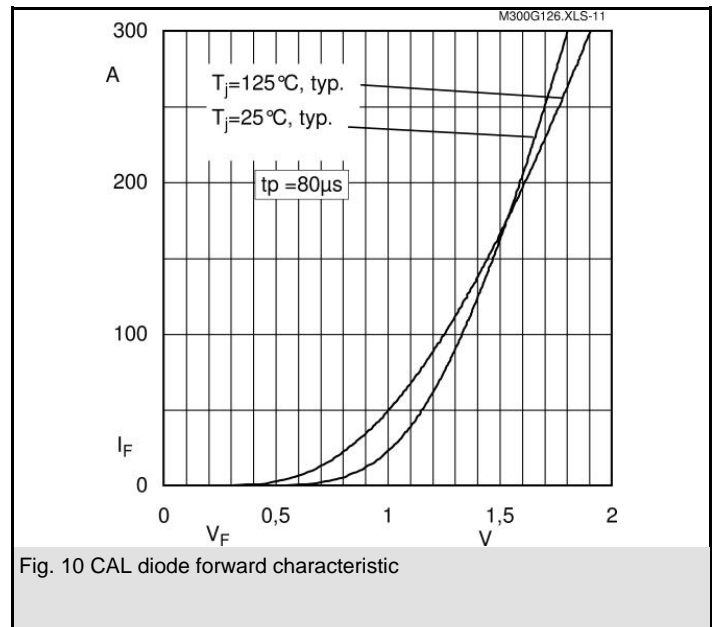


Fig. 10 CAL diode forward characteristic

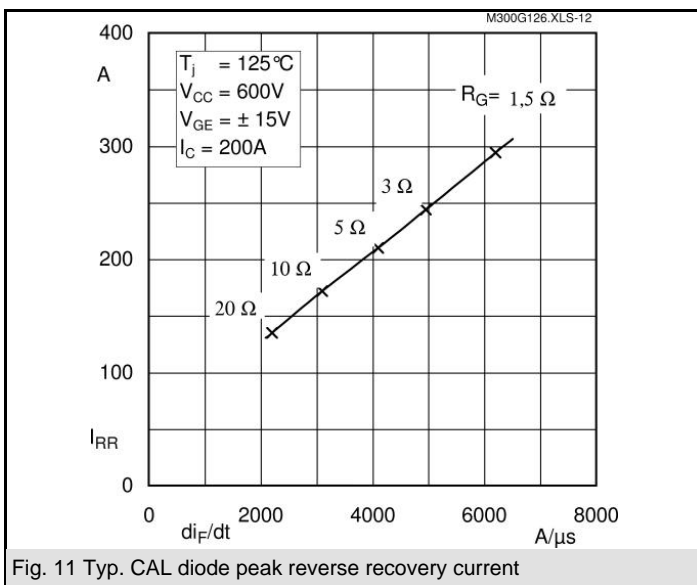


Fig. 11 Typ. CAL diode peak reverse recovery current

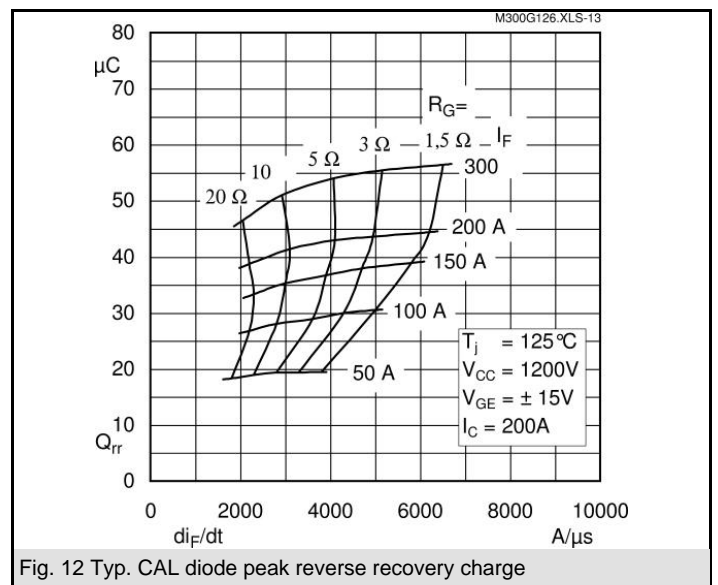


Fig. 12 Typ. CAL diode peak reverse recovery charge

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UL Recognized

CASED56

File 63 532



Case D 56



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Case D 56